

## High Speed IGBT in Trench and Fieldstop Technology

### Electrical Features:

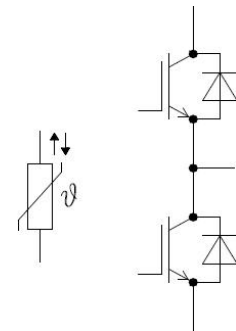
- 1200V 600A,  $V_{CE(sat)} = 2.0V @ 25^{\circ}C$
- High RBSOA Capability
- Trench/FS Technology
- Low Reverse-recovery Losses
- High SC Capability

### Applications:

- Motor Drives
- Solar Applications
- UPS Systems
- Commercial Electric Vehicles
- Wind Turbines

### Mechanical Features:

- High Power and Thermal Cycling Capability
- High Power Density
- PressFIT Contact Technology
- Isolated Base Plate



Equivalent circuit

### Key Performance and Package Parameters

Type	$V_{CE}$	$I_C$	$V_{CE(sat)}, T_{vj}=25^{\circ}C$	$T_{vjmax}$	Marking	Package
DKM600GB12X7E	1200V	600A	2.0V	150°C	DKM600GB12X7E	EconoDual3

### Maximum Ratings and Characteristics

#### Absolute Maximum Ratings at $T_c = 25^{\circ}C$ (unless otherwise specified)

Items	Symbols	Values	Units	Remarks
Collector-Emitter voltage	$V_{CES}$	1200	V	
Gate-Emitter voltage	$V_{GES}$	$\pm 30$	V	
DC Collector Current	$I_C$	600	A	$T_C = 100^{\circ}C$
Pulsed Collector Current	$I_{CP}$	1200	A	Note *1
Diode Forward Current	$I_F$	600	A	
Short Circuit Withstand Time	$T_{SC}$	10	$\mu s$	$V_{CC} \leq 600V, V_{GE} = 15V$ $T_{vj} \leq 150^{\circ}C$
Operating Junction Temperature	$T_{vj}$	-40 ~ +150	$^{\circ}C$	
Storage Temperature	$T_{stg}$	-40 ~ +125	$^{\circ}C$	

Note \*1 : Pulse width limited by  $T_{vjmax}$ .

**Electrical characteristics (unless otherwise specified)**

**IGBT**

Description	Symbols	Conditions	Values			Unit	
			Min	Typ	Max		
Zero Gate Voltage Collector Current	$I_{CES}$	$V_{CE} = 1200V, V_{GE} = 0V$ $T_{vj} = 25^{\circ}C$			200	$\mu A$	
Gate-Emitter Leakage Current	$I_{GES}$	$V_{CE} = 0V, V = 20V$			$\pm 300$	nA	
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 600mA$	6.2	6.7	7.2	V	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE} = 15V$ $I_C = 600A$	$T_{vj} = 25^{\circ}C$		2.0	2.4	V
			$T_{vj} = 125^{\circ}C$		2.5		
			$T_{vj} = 150^{\circ}C$		2.7		
Input Capacitance	$C_{ies}$	$V_{CE} = 25V, V_{GE} = 0V$		105.0		nF	
Reverse Transfer Capacitance	$C_{res}$	$f = 1MHz$		0.72		nF	
Gate Charge	$Q_G$	$V_{CC} = 600V, V_{GE} = 15V$		2270		nC	
Internal Gate Resistor	$R_{Gint}$	$T_{vj} = 25^{\circ}C$		0.90		$\Omega$	
Turn-On Delay Time, Inductive load	$t_{d(on)}$	$V_{CC} = 600V$ $I_C = 600A$ $V_{GE} = 15V$ $R_G = 15\Omega$	$T_{vj} = 25^{\circ}C$		1.09		$\mu s$
			$T_{vj} = 125^{\circ}C$		1.02		
			$T_{vj} = 150^{\circ}C$		0.98		
Rise Time, Inductive load	$t_r$		$T_{vj} = 25^{\circ}C$		0.53		$\mu s$
			$T_{vj} = 125^{\circ}C$		0.55		
			$T_{vj} = 150^{\circ}C$		0.57		
Turn-Off Delay Time, Inductive load	$t_{d(off)}$		$T_{vj} = 25^{\circ}C$		1.60		$\mu s$
			$T_{vj} = 125^{\circ}C$		1.65		
			$T_{vj} = 150^{\circ}C$		1.67		
Fall Time, Inductive load	$t_f$	$T_{vj} = 25^{\circ}C$		0.12		$\mu s$	
		$T_{vj} = 125^{\circ}C$		0.12			
		$T_{vj} = 150^{\circ}C$		0.13			
Turn-On Energy	$E_{on}$	$T_{vj} = 25^{\circ}C$		171		mJ	
		$T_{vj} = 125^{\circ}C$		210			
		$T_{vj} = 150^{\circ}C$		223			
Turn-Off Energy	$E_{off}$	$T_{vj} = 25^{\circ}C$		87		mJ	
		$T_{vj} = 125^{\circ}C$		95			
		$T_{vj} = 150^{\circ}C$		97			

**Diode**

Description	Symbols	Conditions	Values			Unit
			Min	Typ	Max	
Forward Voltage	$V_F$	$I_F= 600A$ $V_{GE}= 0V$	$T_{vj}= 25^{\circ}C$	2.9	3.5	V
			$T_{vj}= 125^{\circ}C$	2.25		
			$T_{vj}= 150^{\circ}C$	2.15		
Recovery Charge	$Q_r$	$I_F= 600A, V_R= 600V$ $-di_F/dt= 1000A/us, V_{GE}= -8V$	$T_{vj}= 25^{\circ}C$	20.1		$\mu C$
			$T_{vj}= 125^{\circ}C$	36.9		
			$T_{vj}= 150^{\circ}C$	48.5		
Reverse Recovery Energy	$E_{rec}$	$I_F=600A, V_R=600V$ $-di_F/dt=1000A/us V_{GE}= -8V$	$T_{vj}= 25^{\circ}C$	3.9		mJ
			$T_{vj}= 125^{\circ}C$	10.6		
			$T_{vj}= 150^{\circ}C$	12.7		

**Thermal resistance**

Items	Symbols	Values			Unit
		Min	Typ	Max	
Thermal Resistance, Per IGBT Junction to Case	$R_{th(j-c)}$			0.081	K/W
Thermal Resistance, Per Diodes Junction to Case	$R_{th(j-c)}$			0.136	

**Module**

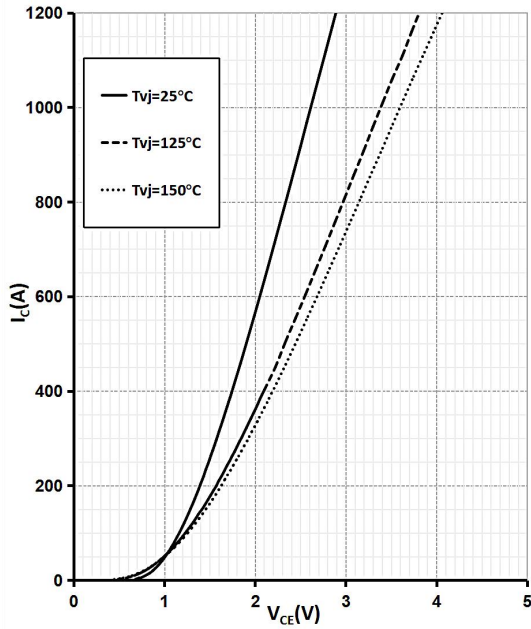
Description	Symbols	Conditions	Values	Unit
Isolation Test Voltage	$V_{ISOL}$	RMS, $f=50Hz, t= 1min$	4.0	KV
Material of Module Base plat			Cu	
Internal Isolation			$Al_2O_3$	
Creepage Distance	$d_{Creep}$	Terminal to heatsink	14.5	mm
		Terminal to terminal	12.8	
Clearance	$d_{clear}$	Terminal to heatsink	12.5	mm
		Terminal to terminal	10.1	
Comparative Tracking Index	CTI		200	

Description	Symbols	Conditions	Values			Unit
			Min	Typ	Max	
Stray Inductance Module	$L_{sCE}$			19		nH
Module Lead Resistance , Terminals-Chip	$R_{CC'+EE'}$	$T_C= 25^{\circ}C, Per switch$		1.05		m $\Omega$
Mounting Torque for Module Mounting	M	Screw M5	3.0		6.0	Nm
Weight	G			348		g

**Output characteristic (typical), IGBT, Inverter**

$I_C = f(V_{CE})$

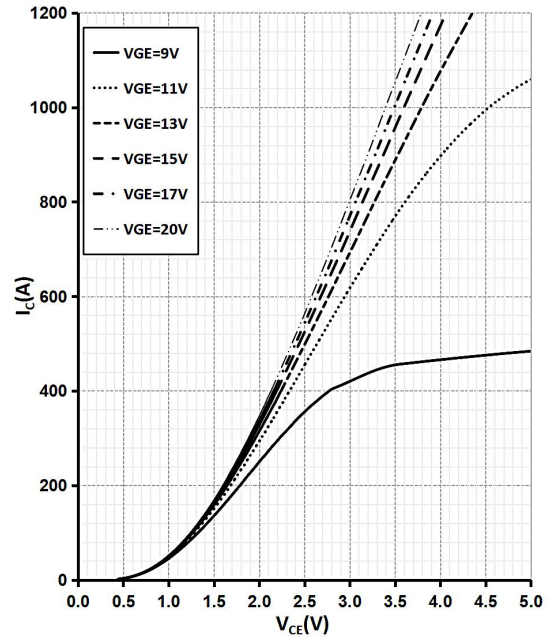
$V_{GE} = 15V$



**Output characteristic (typical), IGBT, Inverter**

$I_C = f(V_{CE})$

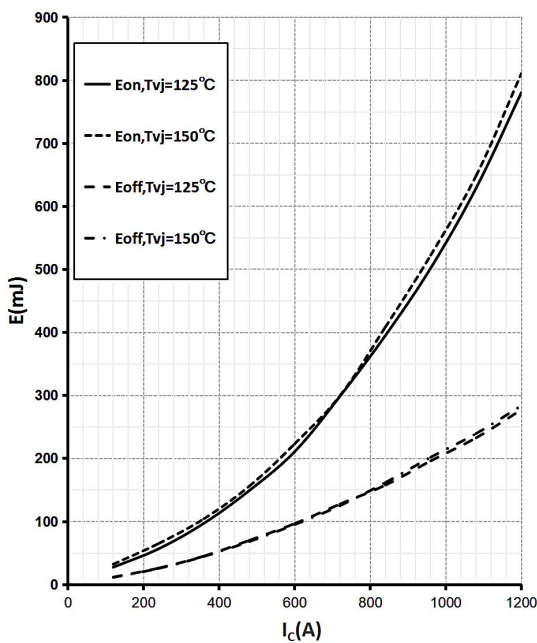
$T_{vj} = 150^{\circ}C$



**Switching losses (typical), IGBT, Inverter**

$E = f(I_C)$

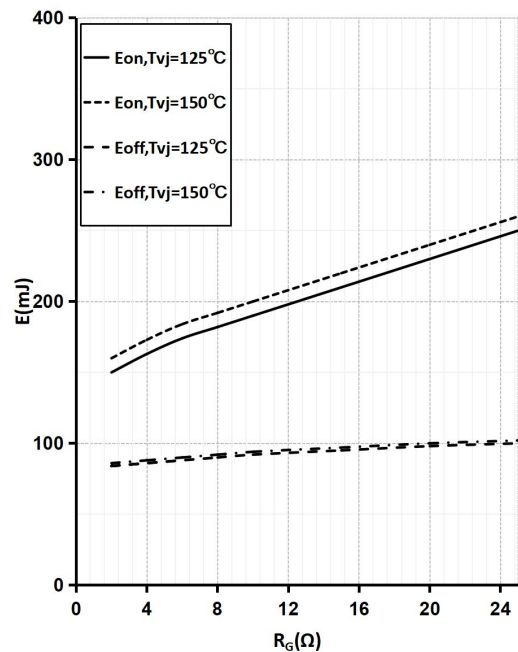
$R_{Goff} = 15\Omega, R_{Gon} = 15\Omega, V_{GE} = \pm 15V, V_{CC} = 600V$



**Switching losses (typical), IGBT, Inverter**

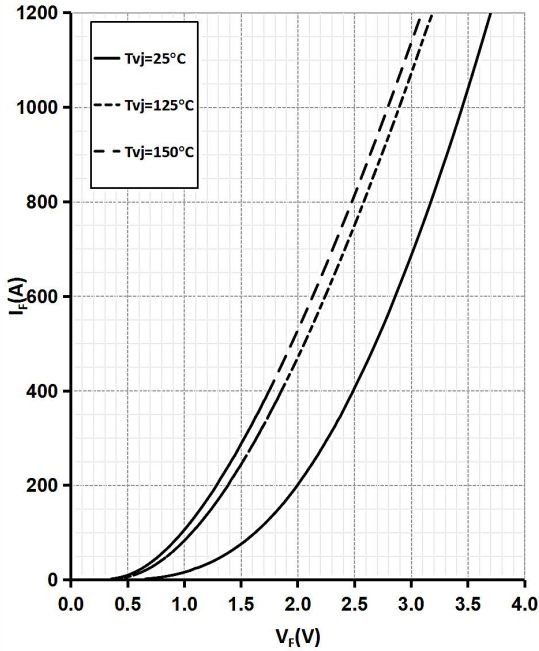
$E = f(R_G)$

$V_{GE} = 15V, I_C = 600A, V_{CC} = 600V$



**Forward characteristic (typical), Diode, Inverter**

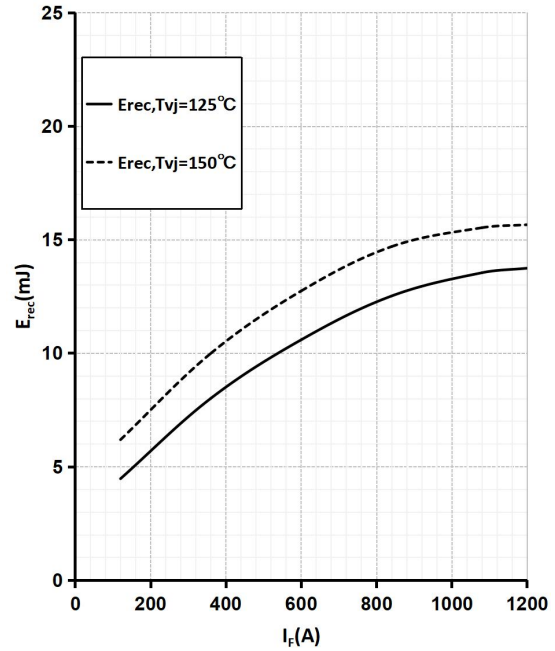
$I_F = f(V_F)$



**Switching losses (typical), Diode, Inverter**

$E_{rec} = f(I_F)$

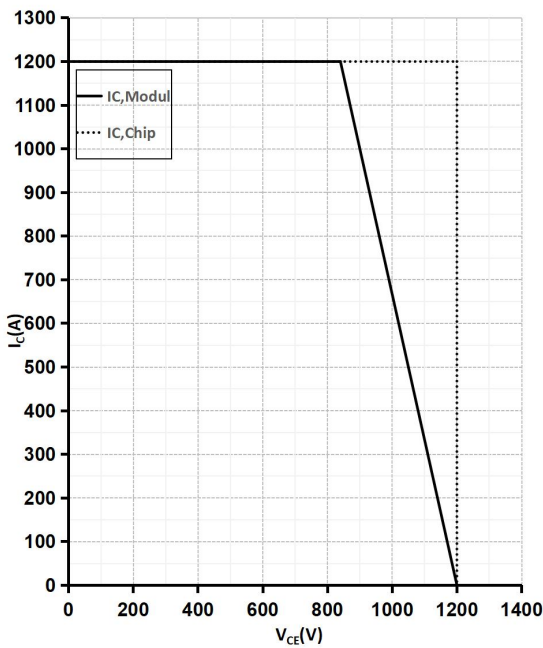
$R_{Gon} = 15\Omega, V_{CC} = 600V$



**Reverse bias safe operating area (RBSOA), IGBT, Inverter**

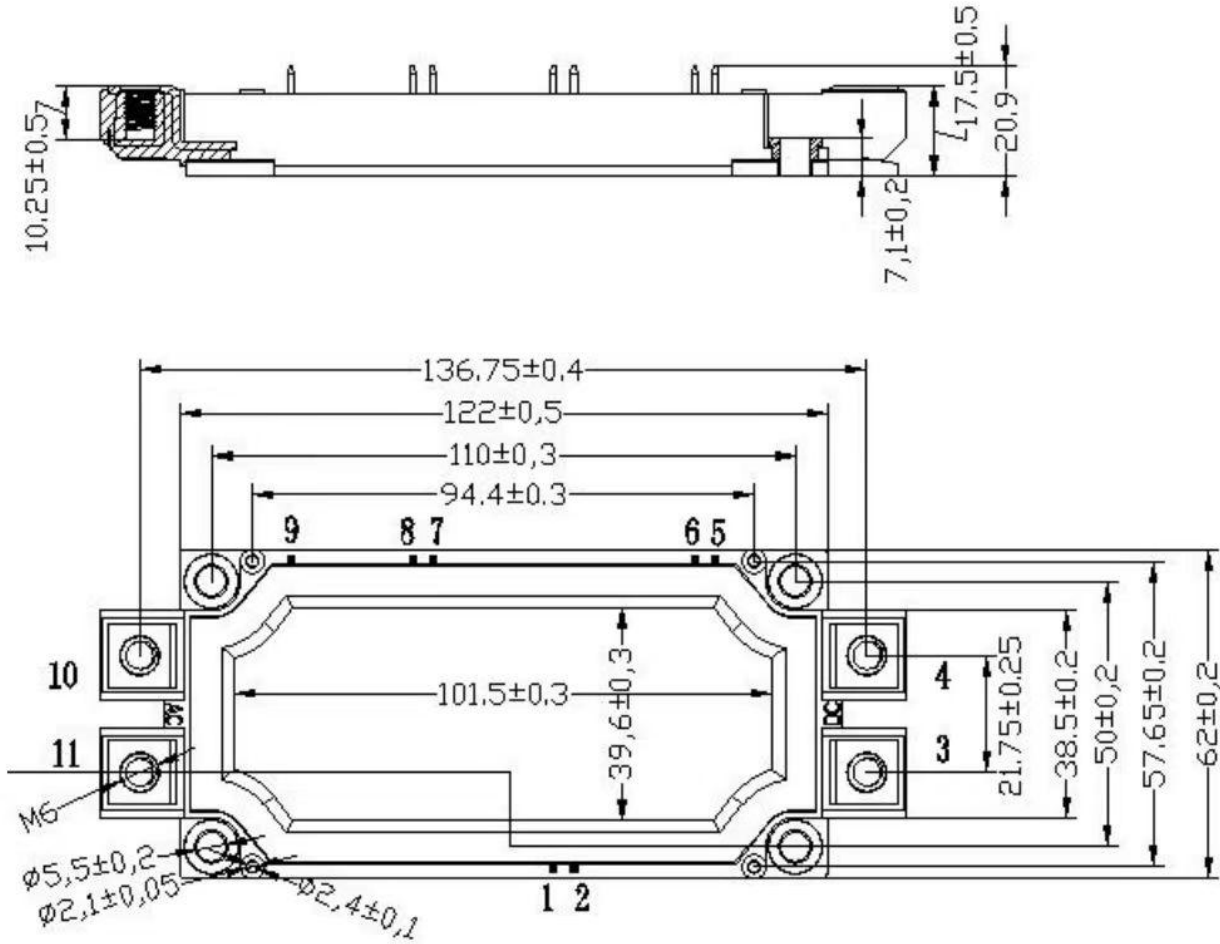
$I_C = f(V_{CE})$

$R_{Goff} = 15\Omega, V_{GE} = \pm 15V, T_{vj} = 150^\circ C$

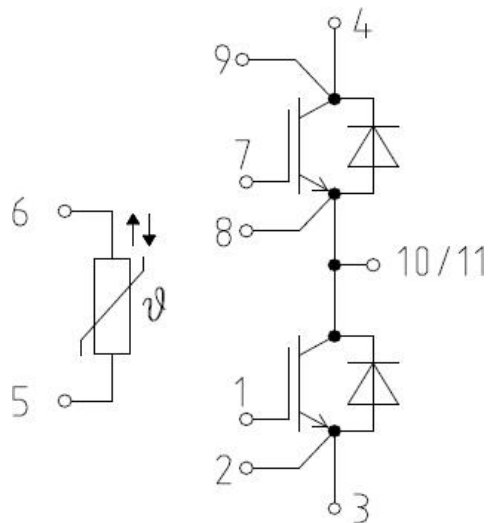


### Package Dimension

Dimensions in Millimeters



Internal Circuit



## Revision History

Revision	Date	Subjects (major changes since last revision)
0.1	2024-04-09	Preliminary version

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